

Part Number: XLFBB20DLSDLCR

OVAL SOLID STATE LAMP

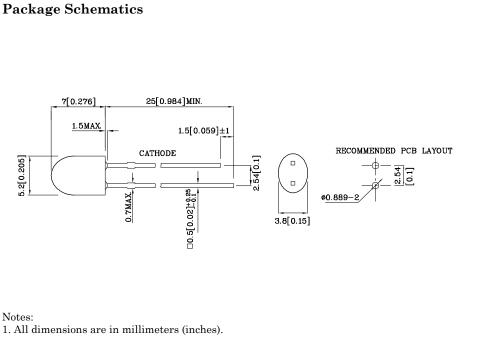
Features

- Radial / Through hole package
- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- \bullet RoHS Compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	FBB (InGaN)			
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	$I_{\rm F}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	le ifs		mA	
Power Dissipation	\mathbf{P}_{D}	120	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$	-C	
Electrostatic Discharge Threshold (HBM)	250	V		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

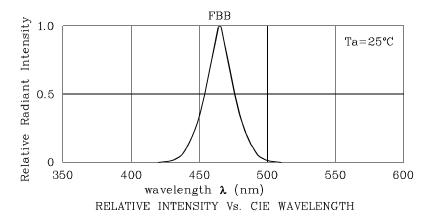
Operating Characteristics (T _A =25°C)	FBB (InGaN)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.3	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4	V
Reverse Current (Max.) (V _R =5V)	I_R	50	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	465*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	470*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	22	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	pF

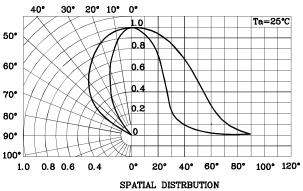
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XLFBB20DLSDLCR	Blue	InGaN	Blue Semi Dif- fused	700*	1195*	465*	100°(H) 50°(V)

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

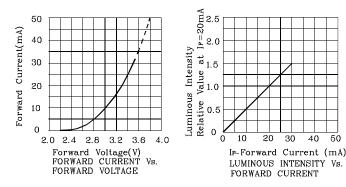
Dec 16,2013

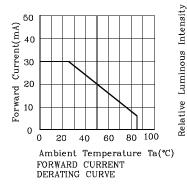




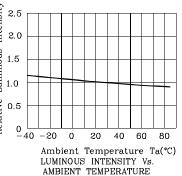


FBB

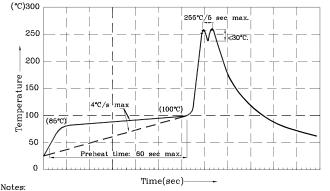




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Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



I.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec

(5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85° C. 4.Fixtures should not incur stress on the component when mounting and

during soldering process. 5.SAC 305 solder alloy is recommended.

6. No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

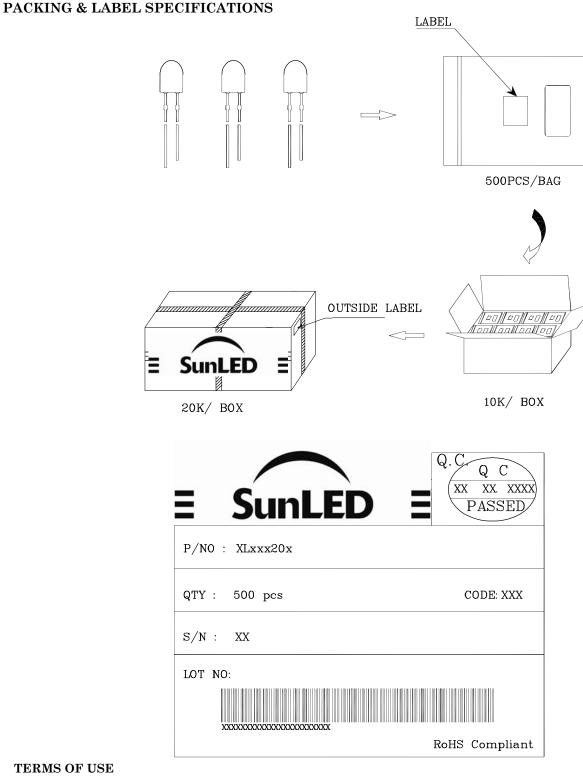
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

Dec 16,2013



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TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp